

E13C7H2F-212.500M
[Click part number to visit Part Number Details page](#)
REGULATORY COMPLIANCE (Data Sheet downloaded on May 9, 2018)
[Click badges to download compliance docs](#)

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**ITEM DESCRIPTION**

Quartz Crystal Clock Oscillators XO (SPXO) LVPECL (PECL) 3.3Vdc 6 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD)
212.500MHz ± 50 ppm over -40°C to +85°C

ELECTRICAL SPECIFICATIONS

Nominal Frequency	212.500MHz
Frequency Tolerance/Stability	± 50 ppm Maximum over -40°C to +85°C (Inclusive of all conditions: Calibration Tolerance (at 25°C), Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
Supply Voltage	3.3Vdc $\pm 5\%$
Input Current	100mA Maximum
Output Voltage Logic High (Voh)	Vdd-1.085Vdc Minimum, 2.35Vdc Typical, Vdd-0.88Vdc Maximum
Output Voltage Logic Low (Vol)	Vdd-1.83Vdc Minimum, 1.60Vdc Typical, Vdd-1.555Vdc Maximum
Rise/Fall Time	300pSec Typical, 700pSec Maximum (Measured at 20% to 80% of Waveform)
Duty Cycle	50 ± 5 (%) (Measured at 50% of Waveform)
Load Drive Capability	50 Ohms into Vdd-2.0Vdc
Output Logic Type	LVPECL
Phase Noise	-60dBc/Hz at 10Hz Offset, -95dBc/Hz at 100Hz Offset, -125dBc/Hz at 1kHz Offset, -143dBc/Hz at 10kHz Offset, -145dBc/Hz at 100kHz Offset, -145dBc/Hz at 1MHz Offset, -146dBc/Hz at 10MHz Offset (All Values are Typical)
Logic Control / Additional Output	Tri-State and Complementary Output
Tri-State Input Voltage (Vih and Vil)	Vih of 70% of Vdd Minimum or No Connect to Enable Output and Complementary Output, Vil of 30% of Vdd Maximum to Disable High Impedance Output and Complementary Output
Standby Current	30 μ A Maximum (Without Load)
RMS Phase Jitter	0.4pSec Typical, 1pSec Maximum (Fj=12kHz to 20MHz; Random)
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

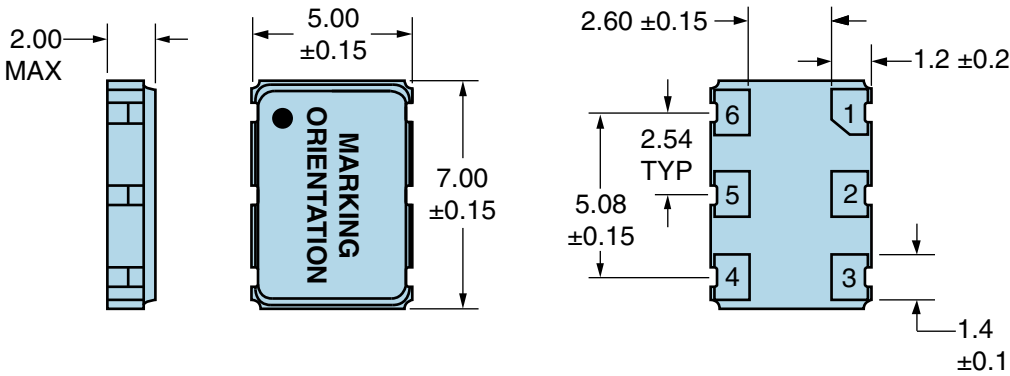
ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

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MECHANICAL DIMENSIONS (all dimensions in millimeters)

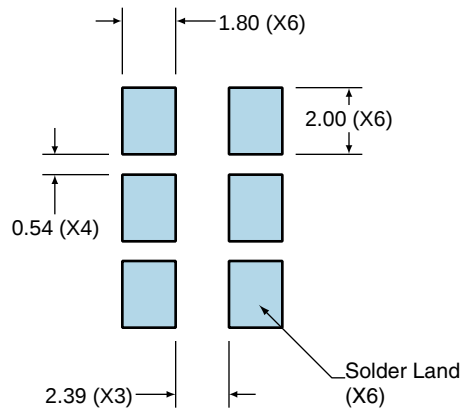


PIN	CONNECTION
1	Tri-State
2	No Connect
3	Case/Ground
4	Output
5	Complementary Output
6	Supply Voltage

LINE	MARKING
1	ECLIPTEK
2	212.50M
3	XXXXX XXXXX=Ecliptek Manufacturing Identifier

Suggested Solder Pad Layout

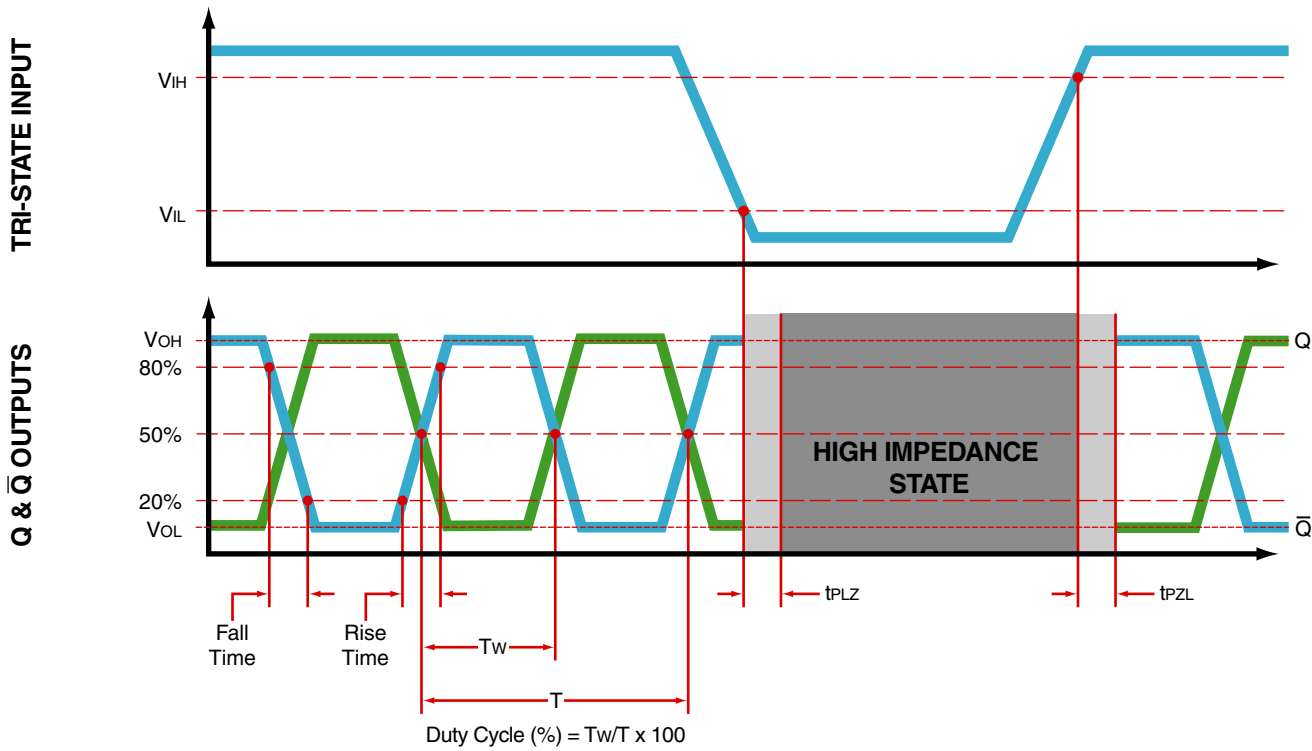
All Dimensions in Millimeters



All Tolerances are ±0.1

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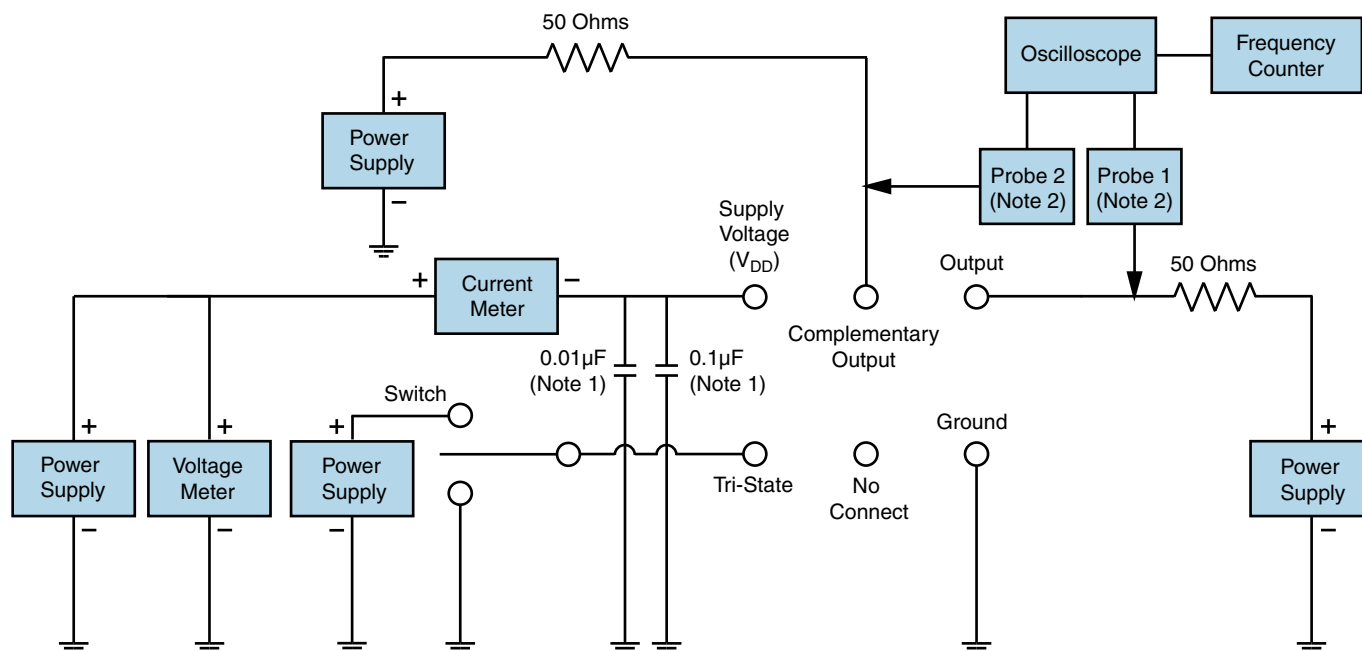
OUTPUT WAVEFORM & TIMING DIAGRAM



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Test Circuit for Tri-State and Complementary Output



Note 1: An external 0.01 μ F ceramic bypass capacitor in parallel with a 0.1 μ F high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>500MHz) passive probe is recommended.

Note 3: Test circuit PCB traces need to be designed for a characteristic line impedance of 50 ohms.

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Recommended Solder Reflow Methods



High Temperature Infrared/Convection

Ts MAX to TL (Ramp-up Rate)	3°C/Second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	150°C
- Temperature Typical (Ts TYP)	175°C
- Temperature Maximum (Ts MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds
Ramp-up Rate (TL to TP)	3°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	217°C
- Time (tL)	60 - 150 Seconds
Peak Temperature (TP)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (TP Target)	250°C +0/-5°C
Time within 5°C of actual peak (tp)	20 - 40 Seconds
Ramp-down Rate	6°C/Second Maximum
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

TS MAX to TL (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (TS MIN)	N/A
- Temperature Typical (TS TYP)	150°C
- Temperature Maximum (TS MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds
Ramp-up Rate (TL to TP)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (TP)	240°C Maximum
Target Peak Temperature (TP Target)	240°C Maximum 2 Times / 230°C Maximum 1 Time
Time within 5°C of actual peak (tP)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)